

Single-Channel: 6N138, 6N139 Dual-Channel: HCPL-2730, HCPL-2731

# Low Input Current High Gain Split Darlington Optocouplers

#### **Features**

- Low current 0.5 mA
- Superior CTR-2000%
- Superior CMR-10 kV/µs
- CTR guaranteed 0-70°C
- U.L. recognized (File # E90700)
- VDE recognized (File # 120915) Ordering option V, e.g., 6N138V
- Dual Channel HCPL-2730
- HCPL-2731

### **Applications**

- Digital logic ground isolation
- Telephone ring detector
- EIA-RS-232C line receiver
- High common mode noise line receiver
- µP bus isolation
- Current loop receiver

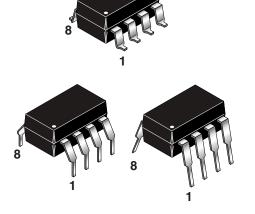
### **Description**

The 6N138/9 and HCPL-2730/HCPL-2731 optocouplers consist of an AlGaAs LED optically coupled to a high gain split darlington photodetector.

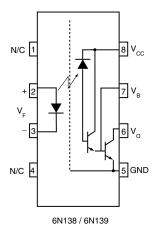
The split darlington configuration separating the input photodiode and the first stage gain from the output transistor permits lower output saturation voltage and higher speed operation than possible with conventional darlington phototransistor optocoupler. In the dual channel devices, HCPL-2730/HCPL2731, an integrated emitter - base resistor provides superior stability over temperature.

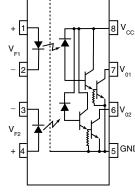
The combination of a very low input current of 0.5 mA and a high current transfer ratio of 2000% makes this family particularly useful for input interface to MOS, CMOS, LSTTL and EIA RS232C, while output compatibility is ensured to CMOS as well as high fan-out TTL requirements. An internal noise shield provides exceptional common mode rejection of 10 kV/µs.

#### **Package**



#### **Schematic**





HCPL-2730 / HCPL-2731

# **Absolute Maximum Ratings** (T<sub>A</sub> = 25°C unless otherwise specified)

Parameter		Symbol	Value	Units
Storage Temperature		T <sub>STG</sub>	-55 to +125	°C
Operating Temperature		T <sub>OPR</sub>	-40 to +85	°C
Lead Solder Temperature (Wave solder only. See recommende SMD mounting)	ed reflow profile graph for	T <sub>SOL</sub>	260 for 10 sec	°C
EMITTER				•
DC/Average Forward Input Current	Each Channel	I <sub>F</sub> (avg)	20	mA
Peak Forward Input Current (50% duty cycle, 1 ms P.W.)	Each Channel	I <sub>F</sub> (pk)	40	mA
Peak Transient Input Current - (≤1 μs P.W., 300 pps)		I <sub>F</sub> (trans)	1.0	Α
Reverse Input Voltage	Each Channel	V <sub>R</sub>	5	V
Input Power Dissipation	Each Channel	P <sub>D</sub>	35	mW
DETECTOR				•
Average Output Current	Each Channel	I <sub>O</sub> (avg)	60	mA
Emitter-Base Reverse Voltage	(6N138 and 6N139)	V <sub>ER</sub>	0.5	V
Supply Voltage, Output Voltage	(6N138, HCPL-2730)	V <sub>CC</sub> , V <sub>O</sub>	-0.5 to 7	V
	(6N139, HCPL-2731)		-0.5 to 18	1
Output Power Dissipation	Each Channel	Po	100	mW

# **Electrical Characteristics** ( $T_A = 0$ to $70^{\circ}$ C Unless otherwise specified)

## **Individual Component Characteristics**

Parameter	Test Conditions		Symbol	Device	Min	Typ**	Max	Unit
EMITTER		T <sub>A</sub> =25°C	V <sub>F</sub>	All		1.30	1.7	V
Input Forward Voltage	Each chan	nel (I <sub>F</sub> = 1.6 mA)					1.75	
Input Reverse Breakdown Voltage	$(T_A = 2)$	5°C, I <sub>R</sub> = 10 μA)	BV <sub>R</sub>	All	5.0	20		V
		Each Channel						
Temperature coefficient of forward	voltage (I <sub>F</sub> = 1.6 r	nA)	$(\Delta V_F/\Delta T_A)$	All		-1.8		mV/°C
DETECTOR								
Logic high output current	$(I_F = 0 \text{ mA}, V$	$V_{\rm O} = V_{\rm CC} = 18  \rm V)$	I <sub>OH</sub>	6N139		0.01	100	μΑ
		Each Channel		HCPL-2731				
	$(I_F = 0 \text{ mA},$	$V_O = V_{CC} = 7 \text{ V}$		6N138		0.01	250	
		Each Channel		HCPL-2730				
Logic low supply	(I <sub>F</sub> = 1.6	mA, $V_O = Open$ ) ( $V_{CC} = 18 V$ )	00=	6N138 6N139		0.4	1.5	mA
	(I <sub>F1</sub> = I <sub>F2</sub> = 1.6 i	mA, V <sub>CC</sub> = 18 V)		HCPL-2731		1.3	3	
	$(V_{O1} - V_{O2} = 0)$	Open, V <sub>CC</sub> = 7 V		HCPL-2730				
Logic high supply	(I <sub>F</sub> = 0	mA, $V_O = Open$ , $V_{CC} = 18 V$ )	Іссн	6N135 6N136		0.05	10	μΑ
$(I_{F1} = I_{F2} = 0 \text{ m})$		mA, V <sub>CC</sub> = 18 V)		HCPL-2731		0.10	20	
	(V <sub>O1</sub> - V <sub>O2</sub> = Open, V <sub>CC</sub> = 7 V			HCPL-2730				

<sup>\*\*</sup> All Typicals at  $T_A = 25^{\circ}C$ 

# **Transfer Characteristics** ( $T_A = 0$ to $70^{\circ}$ C Unless otherwise specified)

Parameter	Test Conditions	Symbol	Device	Min	Тур**	Max	Unit
COUPLED	$(I_F = 0.5 \text{ mA}, V_O = 0.4 \text{ V}, V_{CC} = 4.5 \text{ V})$	CTR	6N139	400	1100		%
Current transfer ratio	Each Channel		HCPL-2731		3500		
(Note 1, 2)	$(I_F = 1.6 \text{ mA}, V_O = 0.4 \text{ V}, V_{CC} = 4.5 \text{ V})$		6N139	500	1300		%
	Each Channel		HCPL-2731		2500		
	$(I_F = 1.6 \text{ mA}, V_O = 0.4 \text{ V}, V_{CC} = 4.5 \text{ V})$		6N138	300	1300		%
	Each Channel		HCPL-2730		2500		
Logic low output voltage	$(I_F = 0.5 \text{ mA}, I_O = 2 \text{ mA}, V_{CC} = 4.5 \text{ V})$	V <sub>OL</sub>	6N139		0.08	0.4	V
output voltage (Note 2)	$(I_F = 1.6 \text{ mA}, I_O = 8 \text{ mA}, V_{CC} = 4.5 \text{ V})$		6N139		0.01	0.4	
	Each Channel		HCPL-2731				
	$(I_F = 0.5 \text{ mA}, I_O = 15 \text{ mA}, V_{CC} = 4.5 \text{ V})$		6N139		0.13	0.4	
	Each Channel		HCPL-2731				
	$(I_F = 12 \text{ mA}, I_O = 24 \text{ mA}, V_{CC} = 4.5 \text{ V})$		6N139		0.20	0.4	
	Each Channel	]	HCPL-2731				
	$(I_F = 1.6 \text{ mA}, I_O = 4.8 \text{ mA}, V_{CC} = 4.5 \text{ V})$	]	6N138		0.10	0.4	
	Each Channel		HCPL-2730				

<sup>\*\*</sup> All Typicals at  $T_A = 25^{\circ}C$ 

# Switching Characteristics ( $T_A = 0$ to $70^{\circ}C$ unless otherwise specified., $V_{CC} = 5 \text{ V}$ )

Parameter	Test	Symbol	Device	Min	Тур**	Max	Unit	
Propagation delay	$(R_L = 4.7 \text{ k}\Omega, I_F = 0.5 \text{ mA})$		T <sub>PHL</sub>	6N139			30	μs
time to logic low (Note 2) (Fig. 22)		T <sub>A</sub> = 25°C				4	25	
(Note 2) (Fig. 22)	(R <sub>L</sub> = 4.7 k	$\Omega$ , $I_F = 0.5 \text{ mA}$		HCPL-2731			120	
	Each Channel	T <sub>A</sub> = 25°C				3	100	
	$(R_L = 270)$	$\Omega$ , I <sub>F</sub> = 12 mA)		6N139			2	
		T <sub>A</sub> = 25°C				0.2	1	
	(R <sub>L</sub> = 270	$\Omega$ , I <sub>F</sub> = 12 mA)		HCPL-2730			3	
	Each Channel	T <sub>A</sub> = 25°C		HCPL-2731		0.3	2	
	(R <sub>L</sub> = 2.2 k	$\Omega$ , $I_F = 1.6 \text{ mA}$		6N138			15	
		T <sub>A</sub> = 25°C				1.5	10	
	(R <sub>L</sub> = 2.2 k	$\Omega$ , $I_F = 1.6 \text{ mA}$		HCPL-2731			25	
	Each Channel	T <sub>A</sub> = 25°C		HCPL-2730		1	20	
Propagation delay	(R <sub>L</sub> = 4.7 k	$(R_L = 4.7 \text{ k}\Omega, I_F = 0.5 \text{ mA})$		6N139			90	μs
time to logic high (Note 2) (Fig. 22)	Each Channel			HCPL-2731				
	$(R_L = 4.7 \text{ k}\Omega, I_F = 0.5 \text{ mA}) T_A = 25^{\circ}\text{C}$			6N139		12	60	
		Each Channel		HCPL-2731		22		
	$(R_L = 270 \ \Omega, I_F = 12 \ mA)$			6N139			10	
		T <sub>A</sub> = 25°C				1.3	7	
	$(R_L = 270 Ω, I_F = 12 mA)$ Each Channel			HCPL-2730			15	
		T <sub>A</sub> = 25°C		HCPL-2731		5	10	
	(R <sub>L</sub> = 2.2 k	$\Omega$ , $I_F = 1.6 \text{ mA}$		6N138			50	
		Each Channel		HCPL-2730/1				
	$(R_L = 2.2 \text{ k}\Omega, I_F = 1.6$	6 mA) T <sub>A</sub> = 25°C		6N138		7	35	
		Each Channel		HCPL-2730/1		16		
Common mode transient immunity at logic high	$(I_F = 0 \text{ mA, I})$ $T_A = 25^{\circ}\text{C}, (R_L = 2.2 \text{ k}\Omega) (N_L = 1.0 \text{ mA, I})$	V <sub>CM</sub> l = 10 V <sub>P-P</sub> ) Note 3) (Fig. 23)	ICM <sub>H</sub> I	6N138 6N139	1,000	10,000		V/µs
		Each Channel		HCPL-2730 HCPL-2731				
Common mode transient immunity	$(I_F = 1.6 \text{ mA},  V_{CM}  = 10 \text{ V}_F$ $T_A = 25^{\circ}\text{C}, (N_{CM})$	$R_{L} = 2.2 \text{ k}\Omega$ Note 3) (Fig. 23)	ICM <sub>L</sub> I	6N138 6N139	1,000	10,000		V/µs
at logic low		Each Channel		HCPL-2730 HCPL-2731				

<sup>\*\*</sup> All Typicals at  $T_A = 25^{\circ}C$ 

## **Isolation Characteristics** (T<sub>A</sub> = 0 to 70°C Unless otherwise specified)

Characteristics	Test Conditions	Symbol	Min	Тур**	Max	Unit
Input-output insulation leakage current	(Relative humidity = 45%) (T <sub>A</sub> = 25°C, t = 5 s) (V <sub>I-O</sub> = 3000 VDC) (Note 8)	I <sub>I-O</sub>			1.0	μА
Withstand insulation test voltage	$(RH \le 50\%, T_A = 25^{\circ}C)$ (Note 4) (t = 1 min.)	V <sub>ISO</sub>	2500			V <sub>RMS</sub>
Resistance (input to output)	(Note 4) (V <sub>I-O</sub> = 500 VDC)	R <sub>I-O</sub>		10 <sup>12</sup>		Ω
Capacitance (input to output)	(Note 4, 5) (f = 1 MHz)	C <sub>I-O</sub>		0.6		pF
Input-Input Insulation leakage current	$(RH \le 45\%, V_{I-I} = 500 \text{ VDC}) \text{ (Note 6)}$ t = 5  s, (HCPL-2730/2731 only)	I <sub>I-I</sub>		0.005		μΑ
Input-Input Resistance	(V <sub>I-I</sub> = 500 VDC) (Note 6) (HCPL-2730/2731 only)	R <sub>I-I</sub>		10 <sup>11</sup>		Ω
Input-Input Capacitance	(f = 1 MHz) (Note 6) (HCPL-2730/2731 only)	C <sub>I-I</sub>		0.03		pF

<sup>\*\*</sup> All Typicals at T<sub>A</sub> = 25°C

#### **Notes**

- 1. Current Transfer Ratio is defined as a ratio of output collector current, I<sub>O</sub>, to the forward LED input current, I<sub>F</sub> times 100%.
- 2. Pin 7 open. (6N138 and 6N139 only)
- 3. Common mode transient immunity in logic high level is the maximum tolerable (positive) dV<sub>cm</sub>/dt on the leading edge of the common mode pulse signal V<sub>CM</sub>, to assure that the output will remain in a logic high state (i.e., V<sub>O</sub>>2.0 V). Common mode transient immunity in logic low level is the maximum tolerable (negative) dV<sub>cm</sub>/dt on the trailing edge of the common mode pulse signal, V<sub>CM</sub>, to assure that the output will remain in a logic low state (i.e., V<sub>O</sub><0.8 V).</p>
- 4. Device is considered a two terminal device: Pins 1, 2, 3 and 4 are shorted together and Pins 5, 6, 7 and 8 are shorted together.
- 5. For dual channel devices, C<sub>I-O</sub> is measured by shorting pins 1 and 2 or pins 3 and 4 together and pins 5 through 8 shorted together.
- 6. Measured between pins 1 and 2 shorted together, and pins 3 and 4 shorted together.

# **Electrical Characteristics** (T<sub>A</sub> = 25°C unless otherwise specified)

**Current Limiting Resistor Calculations** 

$$R_1 \text{ (Non-Invert)} = \frac{V_{DD1} - V_{DF} - V_{OL1}}{I_F}$$

$$R_1 \text{ (Invert)} = \frac{V_{DD1} - V_{OH1} - V_{DF}}{I_E}$$

$$\mathsf{R}_2 = \frac{\mathsf{V}_{\mathsf{DD2}} - = \mathsf{V}_{\mathsf{OLX}} \left( @ \ \mathsf{I}_{\mathsf{L}} - \mathsf{I}_{\mathsf{2}} \right)}{\mathsf{I}_{\mathsf{L}}}$$

#### Where:

V<sub>DD1</sub> - Input Supply Voltage

V<sub>DD2</sub> - Output Supply Voltage

V<sub>DF</sub> - Diode Forward Voltage

V<sub>OL1</sub> - Logic "0" Voltage of Driver

V<sub>OH1</sub> - Logic "1" Voltage of Driver

I<sub>F</sub> - Diode Forward Current

V<sub>OLX</sub> - Saturation Voltage of Output Transistor

I<sub>L</sub> - Load Current Through Resistor R2

I2 - Input Current of Output Gate

	INPUT			ОИТРИТ						
IN			CMOS @ 5 V	CMOS @ 10 V	74XX	74LXX	74SXX	74LSXX	74HXX	
			R2 (V)	R2 (V)	R2 (V)	R2 (V)	R2 (V)	R2 (V)	R2 (V)	
CMOS	NON-INV.	2000	1000	2200	750	1000	1000	1000	560	
@ 5 V	INV.	510								
CMOS	NON-INV.	5100								
@ 10 V	INV.	4700								
74XX	NON-INV.	2200								
	INV.	180								
74LXX	NON-INV.	1800								
	INV.	100								
74SXX	NON-INV.	2000								
	INV.	360								
74LSXX	NON-INV.	2000								
	INV.	180								
74HXX	NON-INV.	2000								
	INV.	180								

Fig. 1 Resistor Values for Logic Interface

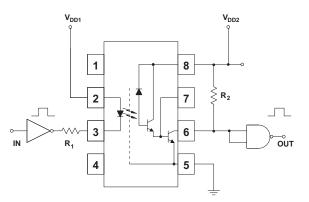


Fig. 2 Non-Inverting Logic Interface

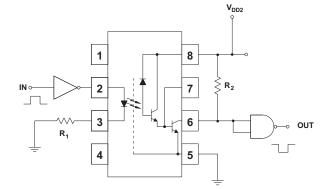


Fig. 3 Inverting Logic Interface



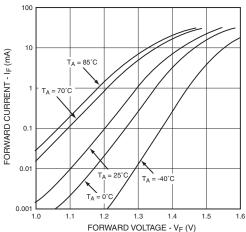


Fig. 6 Non-saturated Rise and Fall Times vs. Load Resistance (6N138 / 6N139 Only)

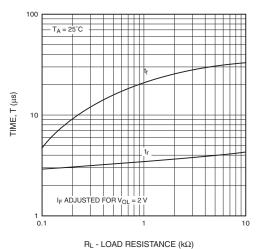


Fig. 8 Propagation Delay To Logic Low vs. Base-Emitter Resistance (HCPL-2730 / HCPL-2731 Only)

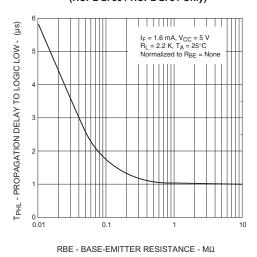


Fig. 5 LED Forward Voltage vs. Temperature

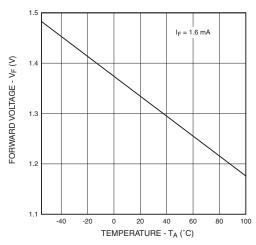


Fig. 7 Non-saturated Rise and Fall Times vs. Load Resistance (HCPL-2730 / HCPL-2731 Only)

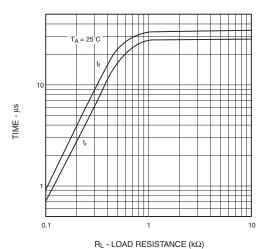
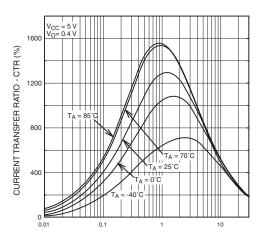
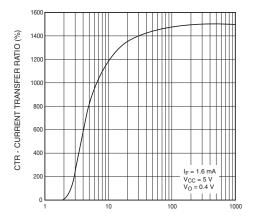


Fig. 9 Current Transfer Ratio vs. Forward Current (6N138 / 6N139 Only)



IF - FORWARD CURRENT - mA

Fig. 10 Current Transfer Ratio vs. Base-Emitter Resistance (6N138 / 6N139 Only)



 $\mathsf{R}_\mathsf{BE}$  - BASE RESISTANCE (k $\Omega$ )

Fig. 12 Output Current vs Output Voltage (6N138 / 6N139 Only)

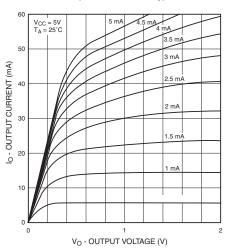


Fig. 14 Output Current vs. Input Diode Forward Current (6N138 / 6N139 Only)

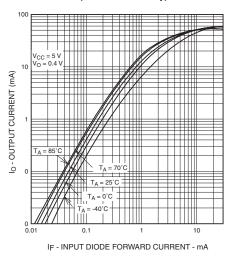
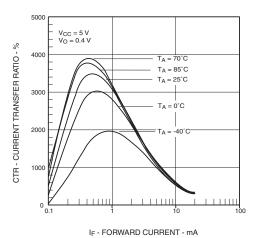


Fig. 11 Current Transfer Ratio vs. Forward Current (HCPL-2730 / HCPL-2731 Only)



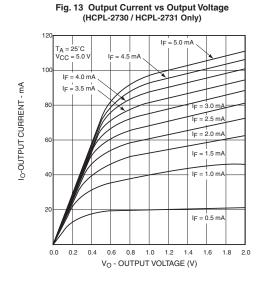
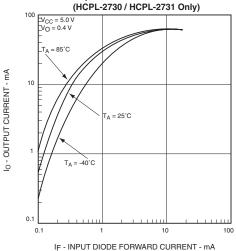


Fig. 15 Output Current vs **Input Diode Forward Current** 



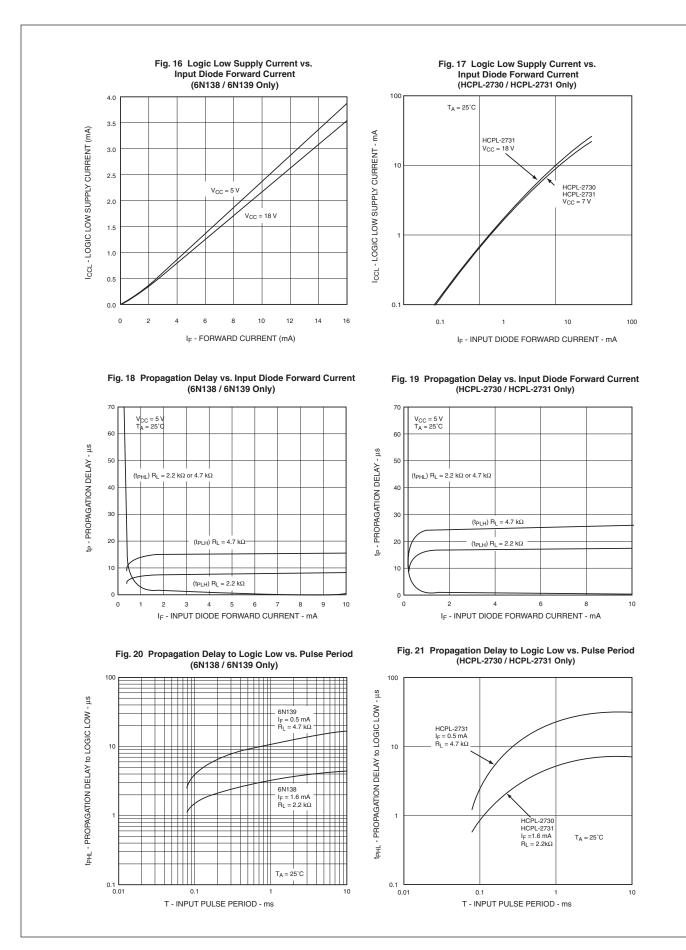


Fig. 22 Propagation Delay vs. Temperature (6N138 / 6N139 Only)

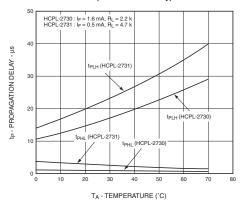
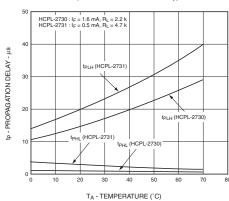


Fig. 23 Propagation Delay vs. Temperature (HCPL-2730 / HCPL-2731 Only)



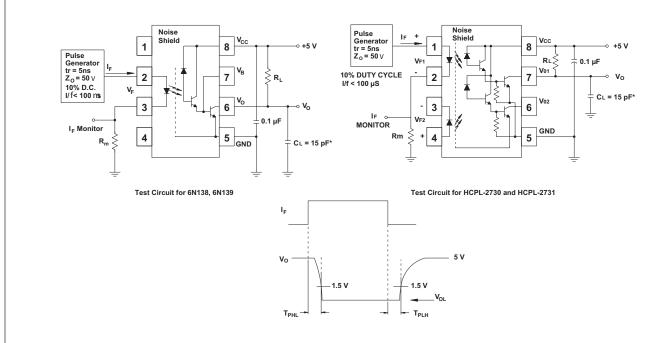
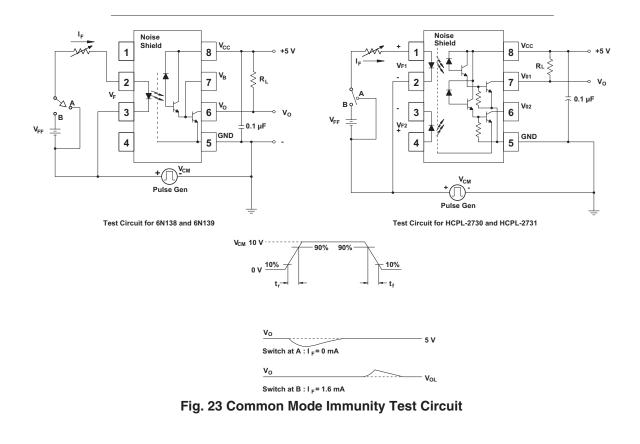
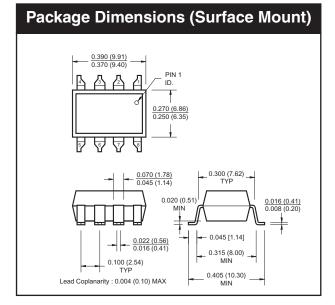
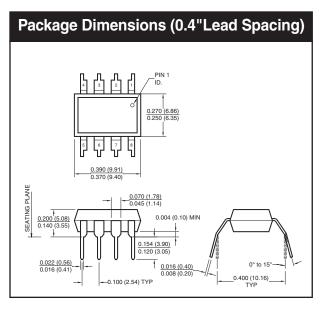


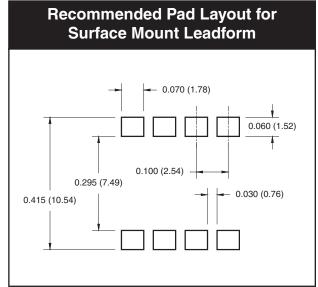
Fig. 22 Switching Time Test Circuit



# **Package Dimensions (Through Hole)** SEATING PLANE 0.200 (5.08) 0.140 (3.55) 0.022 (0.56) 15° MAX-0.300 (7.62)\_ -0.100 (2.54) TYF





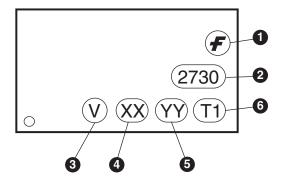


NOTE All dimensions are in inches (millimeters)

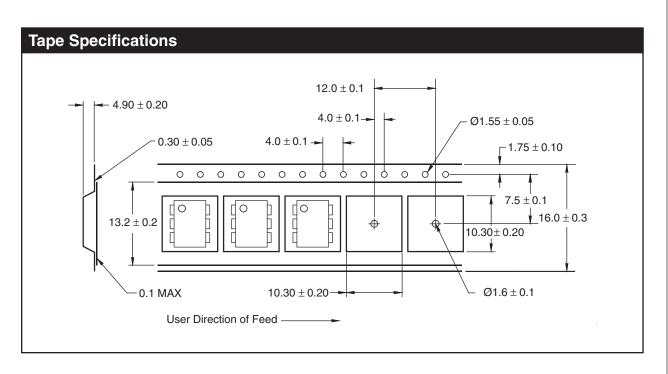
# **Ordering Information**

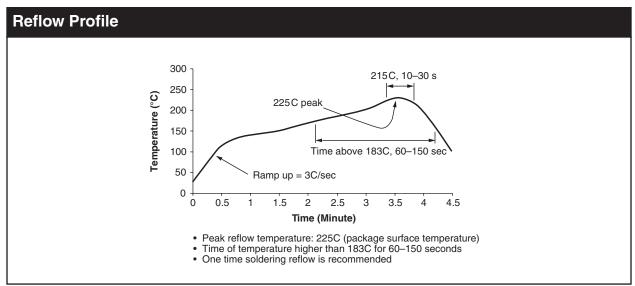
Option	Example Part Number	Description
S	6N138S	Surface Mount Lead Bend
SD	6N138SD	Surface Mount; Tape and reel
W	6N138W	0.4" Lead Spacing
V	6N138V	VDE0884
TV	6N138TV	VDE0884; 0.4" lead spacing
SV	6N138SV	VDE0884; surface mount
SDV	6N138SDV	VDE0884; surface mount; tape and reel

# **Marking Information**



Definiti	Definitions				
1	Fairchild logo				
2	Device number				
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)				
4	Two digit year code, e.g., '03'				
5	Two digit work week ranging from '01' to '53'				
6	Assembly package code				





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Bottomless™	FPS™	MICROCOUPLER™	QFET <sup>®</sup>	TinyLogic <sup>®</sup>
Build it Now™	FRFET™	MicroFET™	QS™	TINYOPTO™
CoolFET™	GlobalOptoisolator™	MicroPak™	QT Optoelectronics™	TruTranslation™
CROSSVOLT™	GTO™ .	MICROWIRE™	Quiet Series™	UHC™
DOME™	HiSeC™	MSX™	RapidConfigure™	$UltraFET^{ ext{ iny B}}$
EcoSPARK™	I <sup>2</sup> C <sup>TM</sup>	MSXPro™	RapidConnect™	UniFET™
E <sup>2</sup> CMOS <sup>TM</sup>	i-Lo™	OCX <sup>TM</sup>	μSerDes™	VCX <sup>TM</sup>
EnSigna™	ImpliedDisconnect™	OCXPro™	SILENT SWITCHER®	Wire™
FACT™	IntelliMAX™	OPTOLOGIC <sup>®</sup>	SMART START™	
FACT Quiet Serie	es <sup>TM</sup>	OPTOPLANAR™	SPM™	
Aaraaa tha baara	I. Around the world.™	PACMAN™	Stealth™	
The Power Fran		POP™	SuperFET™	
Programmable A		Power247™	SuperSOT™-3	
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 A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

#### **PRODUCT STATUS DEFINITIONS**

#### **Definition of Terms**

Datasheet Identification	Product Status	Definition
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